

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph [0108] with the following rewritten paragraph:

Measuring beam 20 is directed under an angle α with the x-y plane, and towards the intersection of the optical axis 24 with the surface of wafer 12, which is to be illuminated, as illustrated by line l which is coincident with an optical axis of the measuring laser beam 20.

At least one additional measuring beam 20' are substantially parallel to measuring beam 20 and are incident on measuring mirror 30. When positioned correctly, the surface of the wafer 12 is in the focal plane of the beam of radiation, and the measuring laser beam is directed towards the intersection of the optical axis of the beam of radiation and the focal plane, now at least locally coinciding with the surface of the wafer.